

Description

The DMP3056LSD uses advanced trench technology and design to provide excellent RDS(ON) with low gat e charge. It can be used in a wide variety of applications.



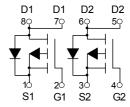
SOP-8

General Features

 $V_{DS} = -30V, I_{D} = -5.3A$

 $R_{DS(ON)} < 42m$ @ $V_{GS}=-10V$

 $R_{DS(ON)} < 85m @ V_{GS}=-4.5V$



Application

PWM application

Load switch

Dual P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP3056LSD	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit	
V _{DS}	Drain-Source Voltage	-30	V	
V _G s	Gate-Source Voltage	±20	V	
l _D	Drain Current-Continuous	-5.3	Α	
Ірм	Drain Current-Pulsed (Note 1)	-20	Α	
P _D	Maximum Power Dissipation	2.6	W	
T _J ,T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$ C	
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	49	°C/W	



Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	-					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =-24V,V _{GS} =0V	-	_	-1	μΑ
Gate-Body Leakage Current	Igss	V _{GS} =±20V,V _{DS} =0V	-	ı	±100	nA
On Characteristics (Note 3)	"					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.6	-3	V
		V _{GS} =-10V, I _D =-5.3A	-	35	42	mR
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =-4.5V, I _D =-4.2A	-	70	85	mR
Forward Transconductance	g FS	V _{DS} =-15V, I _D =-4.5A	4	7	-	S
Dynamic Characteristics (Note4)	II.					
Input Capacitance	Clss		-	540	-	PF
Output Capacitance	Coss	V _{DS} =-15V,V _{GS} =0V,	-	150	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	75	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	td(on)		-	8	-	nS
Turn-on Rise Time	tr	V _{DD} =-15V, ID=-1A,	-	14	-	nS
Turn-Off Delay Time	td(off)	V _{GS} =-10V,R _{GEN} =6	-	18	-	nS
Turn-Off Fall Time	t _f		_	10	-	nS
Total Gate Charge	Qg		-	12	-	nC
Gate-Source Charge	Qgs	V _{DS} =-15V,I _D =-5.3A,V _{GS} =-	_	2.4	-	nC
Gate-Drain Charge	Q _{gd}	. 10 v	-	3.2	-	nC
Drain-Source Diode Characteristics	1		1			
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V, I _S =-5.3A	-	-	-1.2	V

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

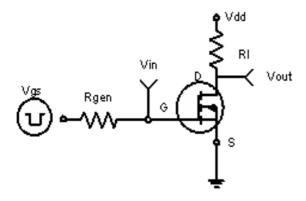


Figure 1:Switching Test Circuit



 T_J -Junction Temperature (°C) **Figure 3 Power Dissipation**

60

80

100

120

140

20

0

40

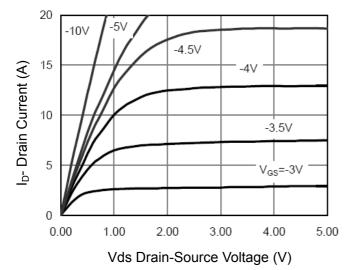


Figure 5 Output Characteristics

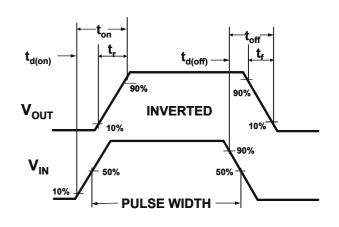


Figure 2:Switching Waveforms

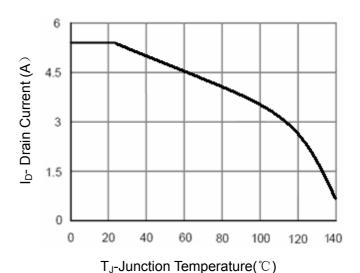


Figure 4 Drain Current

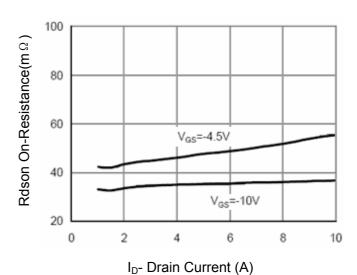


Figure 6 Drain-Source On-Resistance



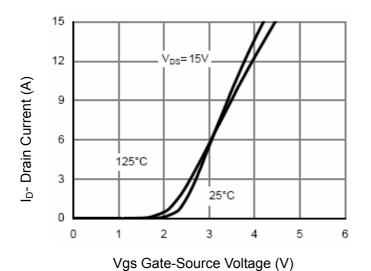


Figure 7 Transfer Characteristics

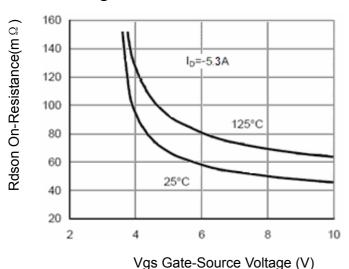


Figure 9 Rdson vs Vgs

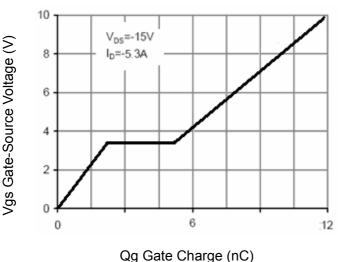


Figure 11 Gate Charge

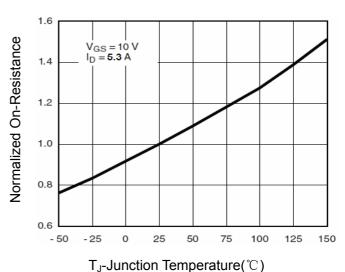


Figure 8 Drain-Source On-Resistance

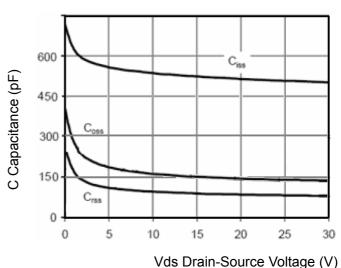
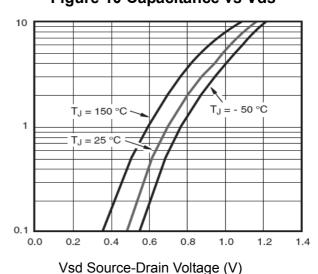


Figure 10 Capacitance vs Vds



Is- Reverse Drain Current (A)

Figure 12 Source- Drain Diode Forward



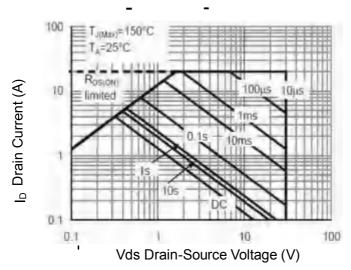
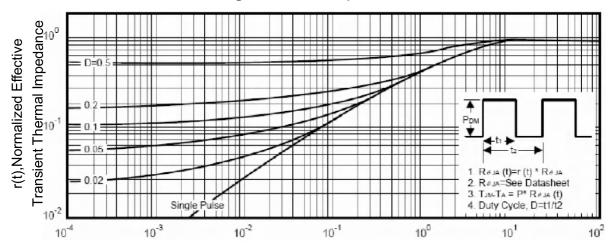


Figure 13 Safe Operation Area

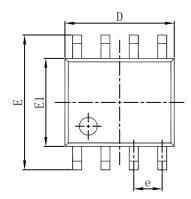


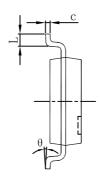
Square Wave Pluse Duration(sec)

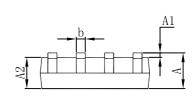
Figure 14 Normalized Maximum Transient Thermal Impedance



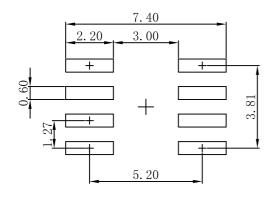
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min	Max	Min	Max		
A	1.350	1.750	0.053	0.069		
A1	0.100	0. 250	0.004	0.010		
A2	1.350	1.550	0.053	0.061		
b	0.330	0.510	0.013	0. 020		
c	0.170	0.250	0.007	0.010		
D	4.800	5.000	0.189	0. 197		
e	1. 270 (1. 270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244		
E1	3.800	4.000	0.150	0. 157		
L	0.400	1.270	0.016	0.050		
θ	0°	8°	0°	8°		



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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